



62mm C-Serien Modul mit Trench/Feldstop IGBT³ und Emitter Controlled³Diode
62mm C-series module with trench/fieldstop IGBT³ and Emitter Controlled³ diode

**Vorläufige Daten
Preliminary Data**

IGBT, Wechselrichter / IGBT, Inverter

Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|--|--|----------------------------|------------|--------|
| Kollektor-Emitter-Sperrspannung Collector-emitter voltage | $T_{vj} = 25^{\circ}\text{C}$ | V_{CES} | 1700 | V |
| Kollektor-Dauergleichstrom Continuous DC collector current | $T_C = 80^{\circ}\text{C}, T_{vj\text{max}} = 150^{\circ}\text{C}$ $T_C = 25^{\circ}\text{C}, T_{vj\text{max}} = 150^{\circ}\text{C}$ | $I_{C\text{nom}}$ I_C | 200 310 | A A |
| Periodischer Kollektor-Spitzenstrom Repetitive peak collector current | $t_P = 1\text{ ms}$ | I_{CRM} | 400 | A |
| Gesamt-Verlustleistung Total power dissipation | $T_C = 25^{\circ}\text{C}, T_{vj\text{max}} = 150$ | P_{tot} | 1250 | W |
| Gate-Emitter-Spitzenspannung Gate-emitter peak voltage | | V_{GES} | +/-20 | V |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|---|---|---|--------------------|--------------|------|--------------------------------|
| Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage | $I_C = 200\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 200\text{ A}, V_{GE} = 15\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | $V_{CE\text{sat}}$ | 2,00 2,40 | 2,45 | V V |
| Gate-Schwellenspannung Gate threshold voltage | $I_C = 8,00\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$ | | $V_{G\text{Eth}}$ | 5,2 | 5,8 | 6,4 V |
| Gateladung Gate charge | $V_{GE} = -15\text{ V} \dots +15\text{ V}$ | | Q_G | 2,30 | | μC |
| Interner Gatewiderstand Internal gate resistor | $T_{vj} = 25^{\circ}\text{C}$ | | $R_{G\text{int}}$ | 3,8 | | Ω |
| Eingangskapazität Input capacitance | $f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$ | | C_{ies} | 18,0 | | nF |
| Rückwirkungskapazität Reverse transfer capacitance | $f = 1\text{ MHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$ | | C_{res} | 0,60 | | nF |
| Kollektor-Emitter-Reststrom Collector-emitter cut-off current | $V_{CE} = 1700\text{ V}, V_{GE} = 0\text{ V}, T_{vj} = 25^{\circ}\text{C}$ | | I_{CES} | | 3,0 | mA |
| Gate-Emitter-Reststrom Gate-emitter leakage current | $V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$ | | I_{GES} | | 400 | nA |
| Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load | $I_C = 200\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{on}} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | $t_{d\text{on}}$ | 0,28 0,30 | | μs μs |
| Anstiegszeit, induktive Last Rise time, inductive load | $I_C = 200\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{on}} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | t_r | 0,08 0,10 | | μs μs |
| Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load | $I_C = 200\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{off}} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | $t_{d\text{off}}$ | 0,80 1,00 | | μs μs |
| Fallzeit, induktive Last Fall time, inductive load | $I_C = 200\text{ A}, V_{CE} = 900\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{off}} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | t_f | 0,12 0,20 | | μs μs |
| Einschaltverlustenergie pro Puls Turn-on energy loss per pulse | $I_C = 200\text{ A}, V_{CE} = 900\text{ V}, L_S = 60\text{ nH}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{on}} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | E_{on} | 58,0 78,0 | | mJ mJ |
| Abschaltverlustenergie pro Puls Turn-off energy loss per pulse | $I_C = 200\text{ A}, V_{CE} = 900\text{ V}, L_S = 60\text{ nH}$ $V_{GE} = \pm 15\text{ V}$ $R_{G\text{off}} = 6,8\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | E_{off} | 43,0 63,0 | | mJ mJ |
| Kurzschlußverhalten SC data | $V_{GE} \leq 15\text{ V}, V_{CC} = 1000\text{ V}$ $V_{CE\text{max}} = V_{CES} - L_{SCE} \cdot di/dt$ | $t_P \leq 10\ \mu\text{s}, T_{vj} = 125^{\circ}\text{C}$ | I_{SC} | 800 | | A |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro IGBT / per IGBT | | R_{thJC} | | 0,10 | K/W |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro IGBT / per IGBT $\lambda_{\text{Paste}} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1\text{ W}/(\text{m}\cdot\text{K})$ | | R_{thCH} | 0,033 | | K/W |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj\text{op}}$ | -40 | 125 | $^{\circ}\text{C}$ |

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**Vorläufige Daten
Preliminary Data**

**Diode, Wechselrichter / Diode, Inverter
Höchstzulässige Werte / Maximum Rated Values**

| | | | | |
|---|--|-----------|------|----------------------|
| Periodische Spitzensperrspannung Repetitive peak reverse voltage | $T_{vj} = 25^{\circ}\text{C}$ | V_{RRM} | 1700 | V |
| Dauergleichstrom Continuous DC forward current | | I_F | 200 | A |
| Periodischer Spitzenstrom Repetitive peak forward current | $t_P = 1\text{ ms}$ | I_{FRM} | 400 | A |
| Grenzlastintegral I^2t - value | $V_R = 0\text{ V}, t_P = 10\text{ ms}, T_{vj} = 125^{\circ}\text{C}$ | I^2t | 6600 | A^2s |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|---|---|---|--------------------|--------------|------|--------------------------------|
| Durchlassspannung Forward voltage | $I_F = 200\text{ A}, V_{GE} = 0\text{ V}$ $I_F = 200\text{ A}, V_{GE} = 0\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | V_F | 1,80 1,90 | 2,20 | V V |
| Rückstromspitze Peak reverse recovery current | $I_F = 200\text{ A}, -di_F/dt = 2700\text{ A}/\mu\text{s} (T_{vj}=125^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | I_{RM} | 210 230 | | A A |
| Sperrverzögerungsladung Recovered charge | $I_F = 200\text{ A}, -di_F/dt = 2700\text{ A}/\mu\text{s} (T_{vj}=125^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | Q_r | 51,0 85,0 | | μC μC |
| Abschaltenergie pro Puls Reverse recovery energy | $I_F = 200\text{ A}, -di_F/dt = 2700\text{ A}/\mu\text{s} (T_{vj}=125^{\circ}\text{C})$ $V_R = 900\text{ V}$ $V_{GE} = -15\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ | E_{rec} | 25,0 48,0 | | mJ mJ |
| Wärmewiderstand, Chip bis Gehäuse Thermal resistance, junction to case | pro Diode / per diode | | R_{thJC} | | 0,16 | K/W |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro Diode / per diode $\lambda_{\text{Paste}} = 1\text{ W}/(\text{m}\cdot\text{K})$ / $\lambda_{\text{grease}} = 1\text{ W}/(\text{m}\cdot\text{K})$ | | R_{thCH} | 0,052 | | K/W |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj\text{ op}}$ | -40 | 125 | $^{\circ}\text{C}$ |

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**Vorläufige Daten
Preliminary Data**

Modul / Module

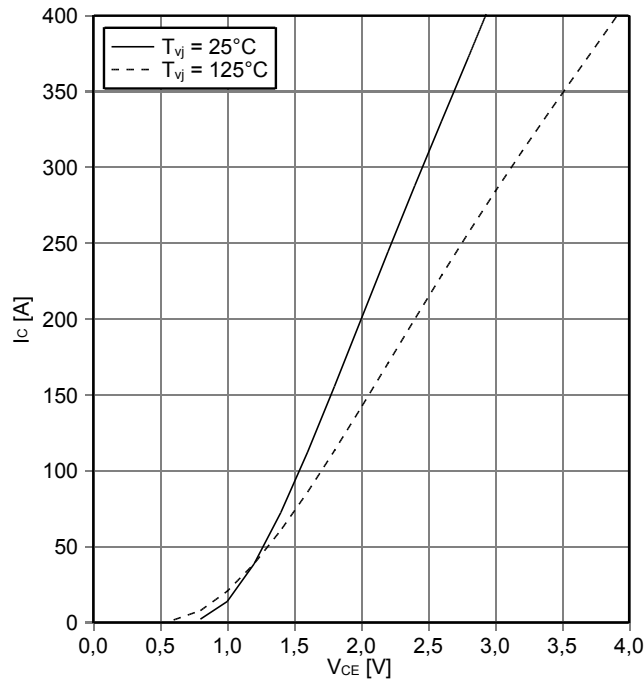
| | | | | | |
|--|--|---------------------|--------------------------------|------|---------|
| Isolations-Prüfspannung Isolation test voltage | RMS, f = 50 Hz, t = 1 min. | V _{ISOL} | 3,4 | | kV |
| Material Modulgrundplatte Material of module baseplate | | | Cu | | |
| Innere Isolation Internal isolation | Basisisolierung (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140) | | Al ₂ O ₃ | | |
| Kriechstrecke Creepage distance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 29,0 23,0 | | mm |
| Luftstrecke Clearance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 23,0 11,0 | | mm |
| Vergleichszahl der Kriechwegbildung Comperative tracking index | | CTI | > 400 | | |
| | | | min. | typ. | max. |
| Wärmewiderstand, Gehäuse bis Kühlkörper Thermal resistance, case to heatsink | pro Modul / per module $\lambda_{\text{Paste}} = 1 \text{ W/(m}\cdot\text{K)} / \lambda_{\text{grease}} = 1 \text{ W/(m}\cdot\text{K)}$ | R _{thCH} | | 0,01 | K/W |
| Modulstreuinduktivität Stray inductance module | | L _{sCE} | | 20 | nH |
| Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip | T _c = 25°C, pro Schalter / per switch | R _{CC+EE'} | | 0,60 | mΩ |
| Lagertemperatur Storage temperature | | T _{stg} | -40 | | 125 °C |
| Anzugsdrehmoment f. Modulmontage Mounting torque for modul mounting | Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note | M | 3,00 | - | 6,00 Nm |
| Anzugsdrehmoment f. elektr. Anschlüsse Terminal connection torque | Schraube M6 - Montage gem. gültiger Applikationsschrift Screw M6 - Mounting according to valid application note | M | 2,5 | - | 5,0 Nm |
| Gewicht Weight | | G | | 340 | g |

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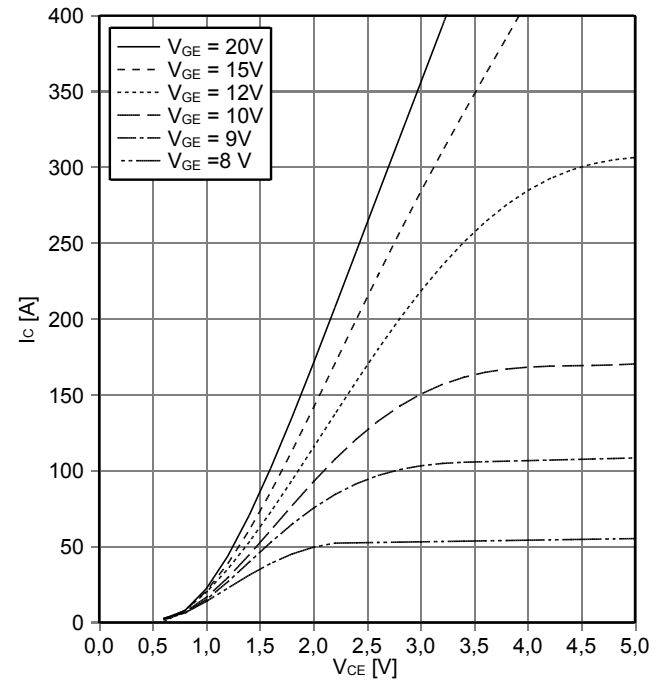
Ausgangskennlinie IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



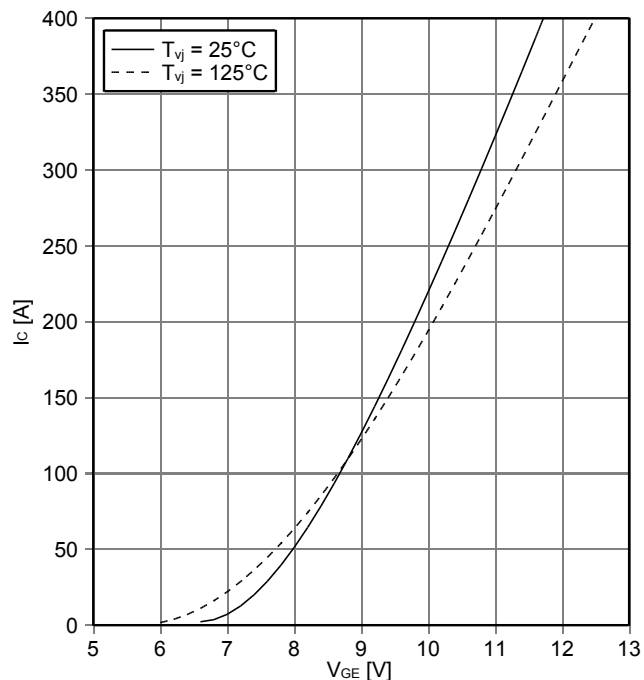
Ausgangskennlinienfeld IGBT, Wechselrichter (typisch)
output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 125^\circ\text{C}$



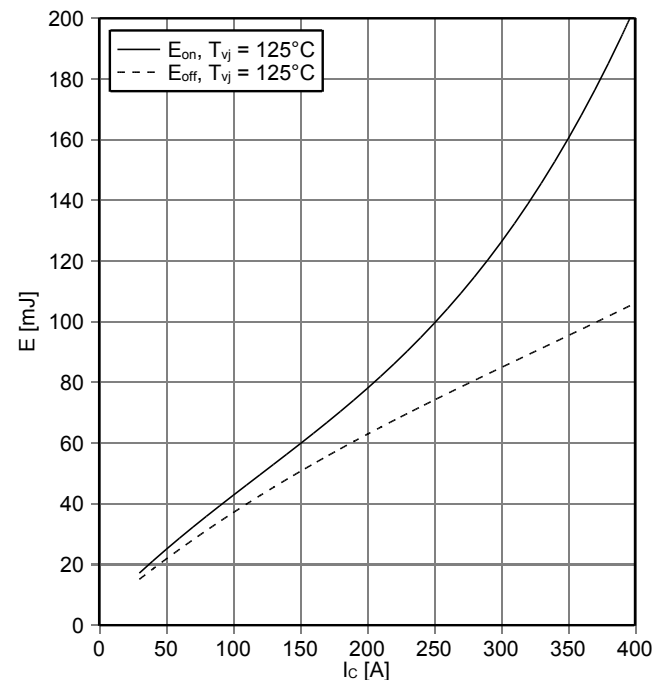
Übertragungscharakteristik IGBT, Wechselrichter (typisch)
transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)

$E_{on} = f(I_C), E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 6.8\ \Omega, R_{Goff} = 6.8\ \Omega, V_{CE} = 900\text{ V}$



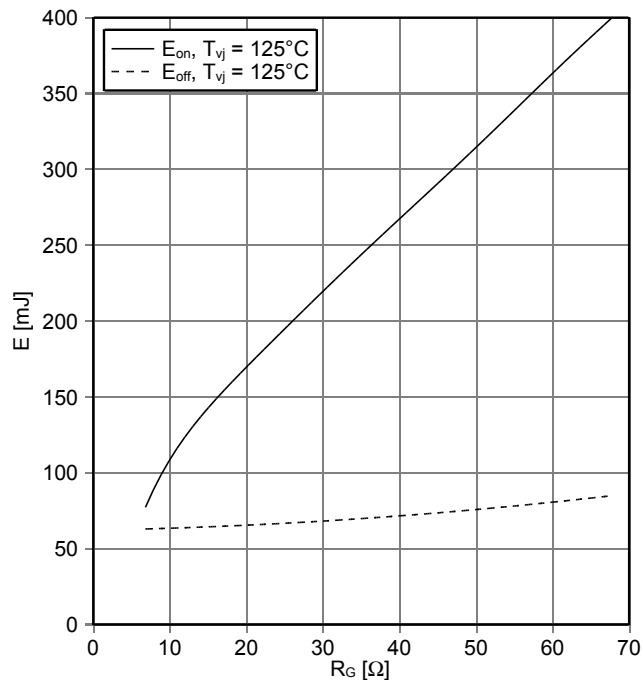
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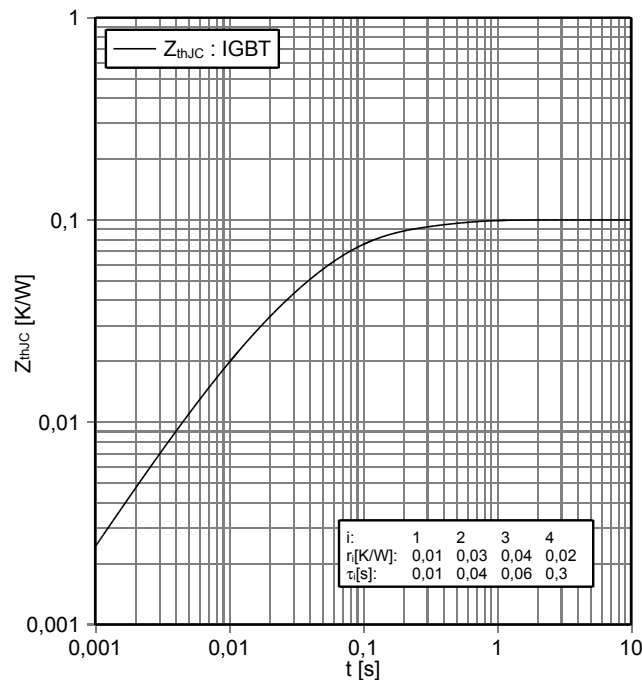
Schaltverluste IGBT, Wechselrichter (typisch)
switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15 V, I_C = 200 A, V_{CE} = 900 V$



Transienter Wärmewiderstand IGBT, Wechselrichter
transient thermal impedance IGBT, Inverter

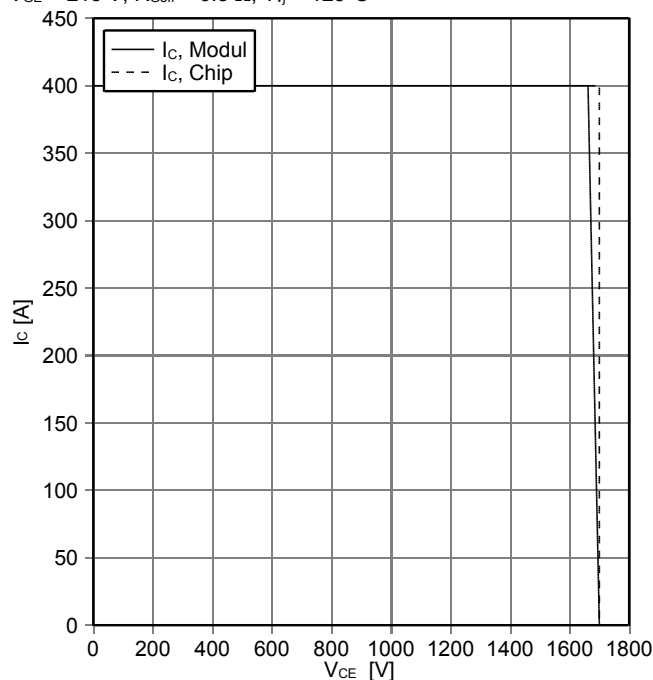
$Z_{thJC} = f(t)$



Sicherer Rückwärts-Arbeitsbereich IGBT, Wechselrichter
(RBSOA)

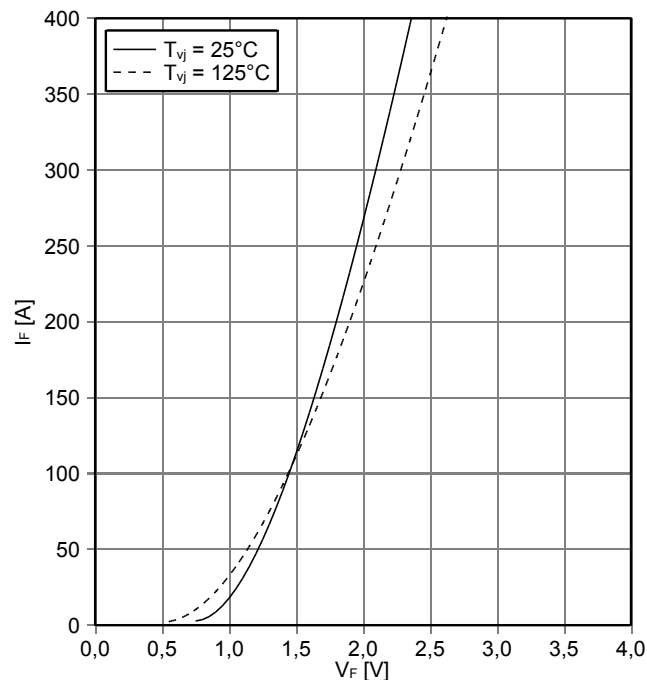
reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$
 $V_{GE} = \pm 15 V, R_{Goff} = 6.8 \Omega, T_{vj} = 125^\circ C$



Durchlasskennlinie der Diode, Wechselrichter (typisch)
forward characteristic of Diode, Inverter (typical)

$I_F = f(V_F)$



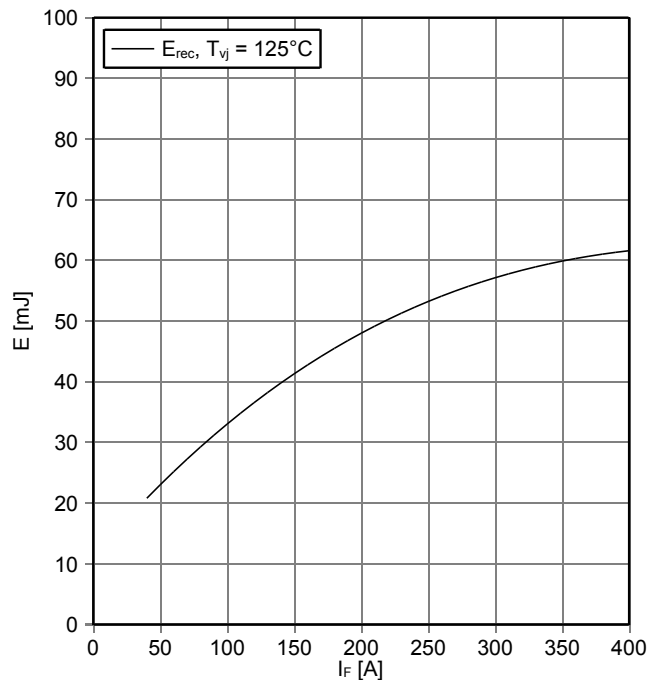
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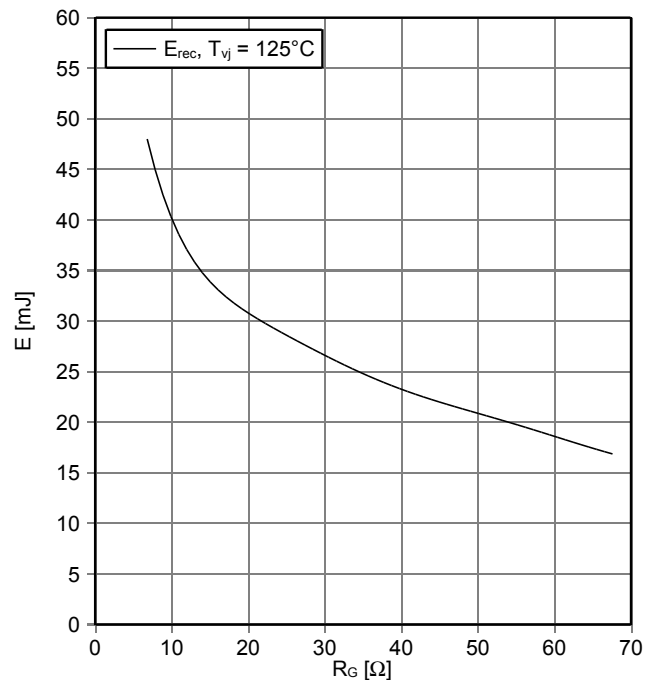
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$
 $R_{Gon} = 6.8 \Omega, V_{CE} = 900 V$



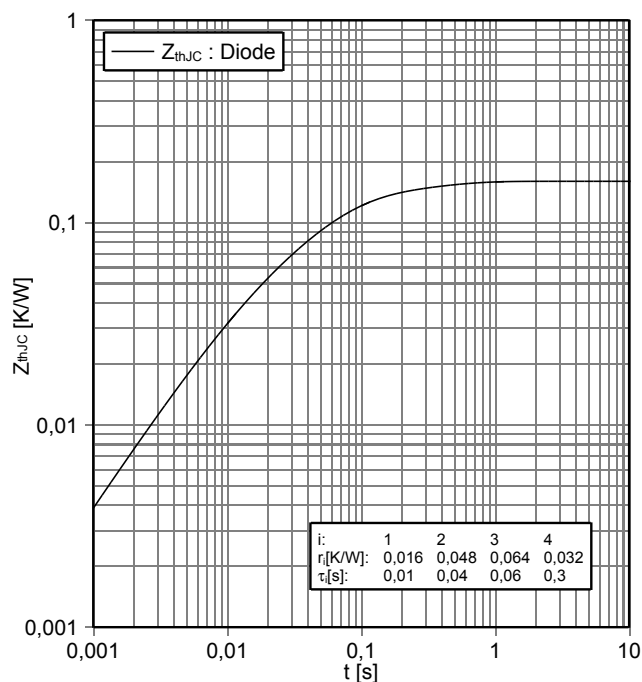
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$
 $I_F = 200 A, V_{CE} = 900 V$



Transienter Wärmewiderstand Diode, Wechselrichter
transient thermal impedance Diode, Inverter

$Z_{thJC} = f(t)$



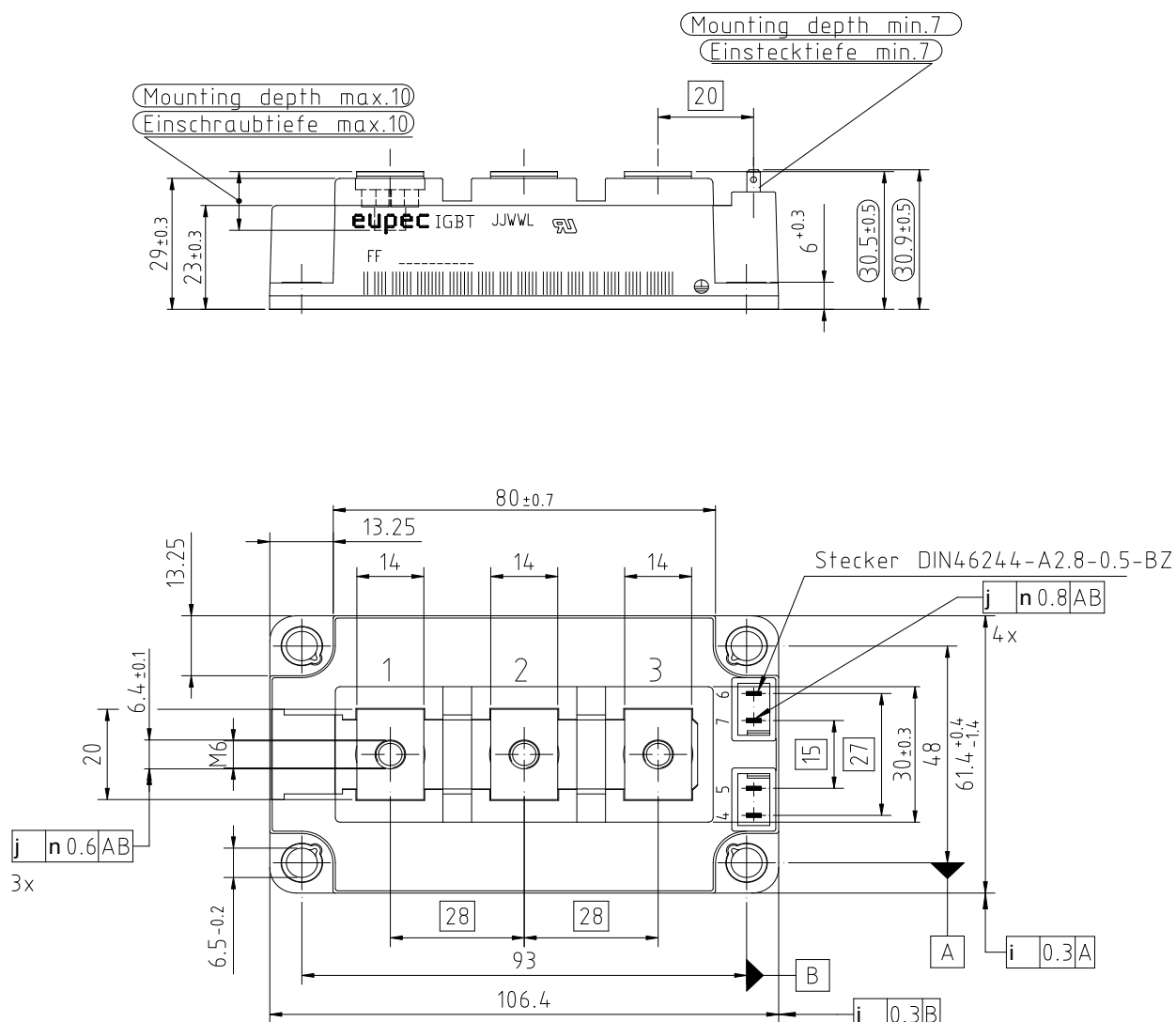
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Vorläufige Daten
Preliminary Data

Schaltplan / circuit_diagram_headline



Gehäuseabmessungen / package outlines



Freimaßtoleranzen
nach ISO2768 mH

General tolerance
ISO2768 mH

Az24

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